



## THERMOFILM H240U

### THERMOFILM H240U

#### DESCRIPTION

Thermofilm® H240U is a heat activated unsupported nitrile phenolic thermosetting transfer adhesive. The product is supplied on a 3.5 mil kraft release liner.

#### APPLICATIONS

- Bonding of plastic parts for electronic assembly
- Splicing of fiberglass cloth and other woven fabric materials
- Heat seaming applications
- Lamination to PVC and other plasticized materials

#### PRODUCT BENEFITS

- Provides high bond strength (considered structural in many applications) to metals, woods, plastics, paper, ceramics, and woven materials when heat activated
- Tack free at room temperature for easy die-cutting
- Relatively low bonding temperature allows use on temperature-sensitive substrates
- Formulated to prevent ooze/squeeze out when heat activated
- Excellent resistance to solvents, plasticizers, and heat when cured

#### TECHNICAL PROPERTIES

Technical Property	Nominal Value	Unit	Test Method
Colour	Clear	-	-
Adhesive Thickness	2.0 (0.051)	Mils (mm)	-
Release Liner Thickness	3.5 (0.089)	Mils (mm)	-

## STANDARD PRESENTATIONS

### RECOMMENDATIONS

#### Application to Primary Substrate:

Unwind H240U and apply the adhesive side to the surface of the substrate to be bonded. To achieve maximum bonding strength, bonding surfaces should be clean, dry and free of grease and oil. The bonding should be performed using a heated (150°F/66°C to 250°F/121°C) squeeze roll or other method, which insures firm pressure and intimate contact of the adhesive film and the substrate surface.

NOTE: After initial bonding, the substrate must be cooled to room temperature before the adhesive regains its non-blocking characteristics.

#### Application to Secondary Substrate:

Peel off the protective release liner and apply the adhesive side to the desired surface using heat and pressure as outlined in the table below:

	Temperature	Dwell	Pressure
For Bonding:	250°F (121°C)	15-45 sec.	30 psi (2.1 kg/cm <sup>2</sup> ) min.
	325°F (163°C)	5-15 sec.	30 psi (2.1 kg/cm <sup>2</sup> ) min.
	400°F (204°C)	1-5 sec.	30 psi (2.1 kg/cm <sup>2</sup> ) min.

A hot platen press is recommended for heat bonding. Peel strength and holding power will vary depending on substrates, heat seal temperature, dwell time, and pressure. Generally speaking, bond strengths are significantly higher than pressure sensitive films and can be classified as structural in some end uses.

NOTE: Shelf life is one year from date of shipment when stored in a cool dry place below 76°F (24°C). Rolls should be stored on end.